



Koh Young Technology Showcasing Advanced Packaging Inspection Solutions at SEMICON Japan at Tokyo Big Sight December 11-13, 2024

Seoul, Korea – Koh Young Technology, the global leader in True 3D measurement-based inspection solutions, will demonstrate its award-winning inspection solutions in Hall 1 Booth 1310 at Tokyo Big Sight on December 12-13, 2024. Our team of experts will be on hand to discuss how our inspection solutions can boost quality and increase yield for advanced and wafer-level packaging. Our team of inspection experts will highlight three different machines: Meister S, Meister D+, and ZenStar.

Meister S

Premium In-line 3D Inspection System for Micro Solder Paste Deposits. The Meister S has been qualified for mass production by major semiconductor foundries and Mini/Micro-LED companies for micro solder inspection with superior full 3D inspection performance. Combining innovative vision algorithms and high-resolution optics, the Meister S goes beyond micro solder paste inspection, but also a proven solution for Flux inspection.

Meister D+

The Meister D+ combines industry-leading Moiré technology and Koh Young's proprietary new optics to support 3D inspection of highly reflective dies, a long-term inspection challenge. Koh Young Technology leverages its expertise in 3D measurement and inspection to address the precise inspection of wafer surfaces, critical dimension measurement, defect detection, and the analysis of complex structures found in semiconductor devices.

ZenStar

The ZenStar, making its debut at SEMICON Japan, supports True 3D inspection of highly reflective dice with a mirror surface. Its unparalleled 2D/3D multi-modal technology combines industry-leading Moiré technology and new Koh Young proprietary optics to provide robust and stable inspection for bleeding-edge applications. With its proprietary deep learning technology, the ZenStar offers enhanced capabilities to inspect defect items like micro-cracks, foreign material, and chipping.



Visit Us and Elevate Your Inspection Capabilities

For more information about how Koh Young's award-winning solutions can elevate your production quality and solve your most challenging inspection needs, visit us at SEMICON Japan Hall 1 Booth 1310. Do not miss this opportunity to engage with our experts, experience our innovative technologies firsthand, and discover how we can help you achieve new levels of efficiency in your manufacturing processes. Learn more about our solutions at www.kohyoung.com.

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About Koh Young Technology, Inc.

Founded in 2002, Koh Young pioneered the industry's first 3D Solder Paste Inspection (SPI) system using patented dual-projection Moiré technology. Today, it leads the market in 3D SPI and Automated Optical Inspection (AOI) solutions, with over 24,000 systems installed worldwide at 3,700 global customers and growing. Koh Young's True 3D technology addresses challenges in electronics manufacturing including surface mount, through-hole, pin insertion, conformal coating, machined parts, semiconductor wafers, and advanced packaging. Guided by user-focused R&D, the company continues to innovate and address evolving market needs. With headquarters in Korea and regional offices worldwide, Koh Young remains close to its customers, delivering trusted solutions for smart manufacturing. Visit www.kohyoung.com to learn more.